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ABSTRACT OF THE DISCLOSURE

A socket and package apparatus are disclosed for increasing the amount of power that can be delivered from an IC board to an IC where the IC package is mounted in a
5 socket connected to the IC board. The apparatus has two separable and distinct parts designed to electrically engage. The package is designed with a power bar where the panels of the power bar are permanently and electrically connected to various power planes of the IC package along its entire adjacent wall. The socket is designed with a power bar carrier designed to maximize the current flow from the IC board to the power
10 bar. The package is then engaged into the socket.